	ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	© Copyright 2005. IPO	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Company unique ID  Unique ID Authority  Response Date*  2024-05-17  2024-05-17  Contact Name  Title - Contact*  Phone - Contact*  Product-Env-Stewards  Product-En	752-21.1										als and Mf	g Informati	on		
Insemi In	upplier Inforr	nation								,					
Title - Contact Name Product Envis Compliance NA Nanufacturing Site Nanufacturing	company name*		Company unique ID			J	Unique ID Authority				Response Date*				
Product Env-Stewards Utthorized Representative* Title - Representative Product Enviro Compliance Product Enviro Compliance Product Enviro Compliance NA Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards @ onsemi.com Product Enviro Compliance NA Product Env-Stewards @ onsemi.com NA	nsemi											2024-05-17			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester Item Number NLV14017BDR2G DECADE COUNTER/DIVIDER DECAD	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  U  Annufacturing Process Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  J-STD-020 MSL Rating  Matte Tin (Sn) - annealed  CU Alloy  1 260  C 30  Seconds  Terminal Plating / Grid Array Material  Manufacturing Process Informative  Product-Env-Stewards@onsemi.com  Manufacturing Site  Weight*  UOM  U  142.68  mg  Effective Date  Version  Manufacturing Site  PH1  142.68  mg  Effective Date  Weight*  Weight*  Weight*  Weight*  Weight*  UOM  U  Annufacturing Process Information  Feminal Base Alloy  J-STD-020 MSL Rating  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  Seconds 3  Comments	Product-Env-Stew	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM UNLV14017BDR2G DECADE COUNTER/DIVIDER 2024-05-17 PH1 142.68 mg Ender Item Number Process Information    Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cycles	uthorized Repres	entative*		Title - Representative			I	Phone - Representative*				Email - Representative*			
NLV14017BDR2G   DECADE COUNTER/DIVIDER   2024-05-17   PH1   142.68   mg   E	Product-Env-Stew	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
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ver 1 - maximum time at peak temperature during soldering is 10-50 seconds		time at neals townswatur	o duning col	domina ia 10 3	20 sacands										
or more information regarding material composition please refer to page 3		<u> </u>													

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and certect to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg
Die Attach	4.85	mg	Supplier	Silver (Ag)	7440-22-4		3.6375	mg
			Supplier	Epoxy resins	129915-35-1		1.2125	mg
Lead Frame	75.92		Supplier	Silver (Ag)	7440-22-4		0.7592	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg
			Supplier	Copper (Cu)	7440-50-8		73.035	mg
Mold Compound-Black	55.11	mg		Epoxy resin	proprietary data		2.7555	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7555	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.1022	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2756	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		48.2213	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	0.34	mg	Supplier	Copper (Cu)	7440-50-8		0.34	mg